



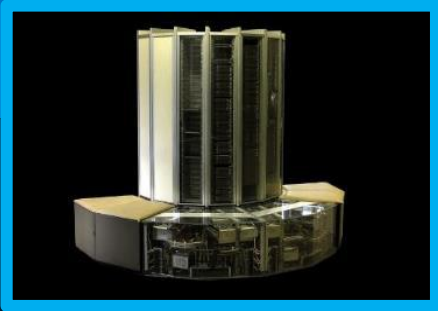
# *Changing Needs/Solutions/Roles*

Rajeeb Hazra

Vice President, Data Center Group  
General Manager, Enterprise & High Performance Computing Platforms  
Intel Corporation

# Three Decades of High Performance Computing

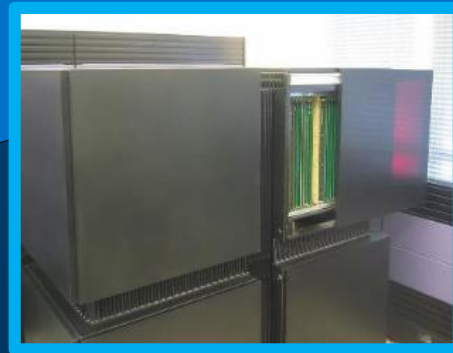
## Vertically integrated



**Cray - 1 (1975)**  
**250 MFLOPS**

- ❑ Fewer fast proprietary processors
- ❑ Custom software
- ❑ ~\$5-8M System Cost
- ❑ Government labs

## Massively Parallel



**Connection Machine - 2 (1987)**  
**2.5 GFLOPS**

- ❑ Unix, VMS and proprietary programming models
- ❑ ~\$5M System Cost
- ❑ Scientific & Commercial

## Democratized HPC



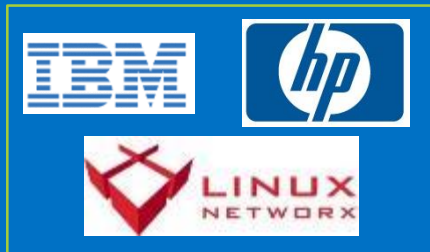
**Beowulf Cluster (1996)**  
**1+ GFLOPS**

- ❑ Commodity compute, network, & storage
- ❑ Standard Linux & parallel programming models
- ❑ ~\$50K System cost
- ❑ Government Labs, Academia & Commercial

# Intel's Role: The x86 "Ecosystem"

The Past: '00-'05

Ad Hoc: Few, incompatible HPC system vendors



Intel: supply silicon

The Present: '06-Today

ICR Platform Spec: ecosystem of many compatible system & apps



Specification delivered to



Intel: enable interoperability

*Is the Future More of the Present?*

# The Writing On The Wall

## Technology Disruptions

*Integration*

*Storage*

*Re-architecture*

*Software Transformation*

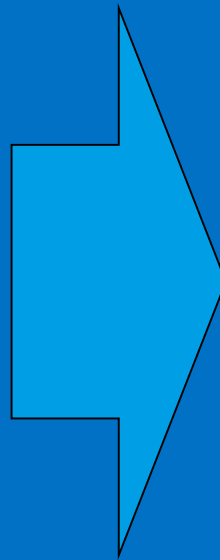
## Increased Demand

*New users & usages ...*

*Cloud makes HPC more accessible*

**PayPal™**

*Real-time analytics using HPC*



## Intensified Competition

 OpenPOWER™

**ARM®** *Indigenous  
CPU interests*

## Channel Challenges

*Increasing complexity*

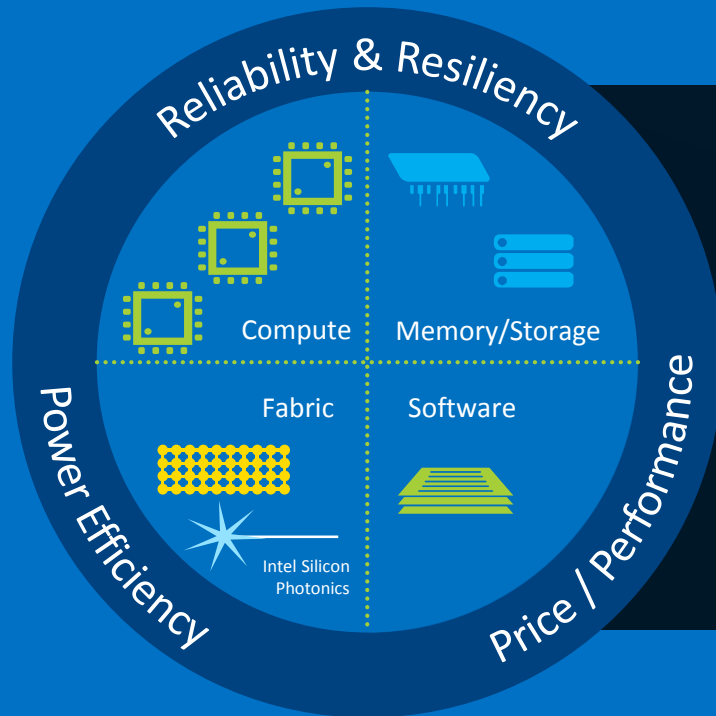
*Software Fragmentation*

*Differentiation*

*New market makers*

# Intel's HPC Scalable System Framework (SSF)

*A design foundation enabling wide range of highly workload-optimized solutions*



Small clusters to Supercomputers

Compute and Data-Centric Computing

Standards-Based Programmability

Intel® Xeon® Processors  
Intel® Xeon Phi™ Coprocessors  
In Package Memory

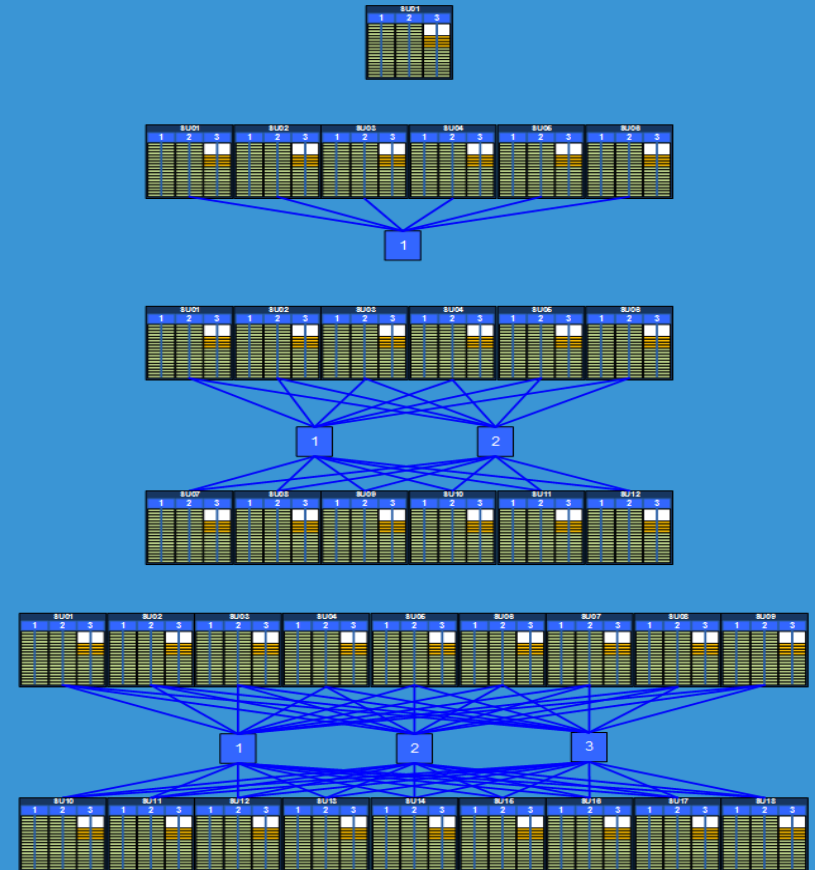
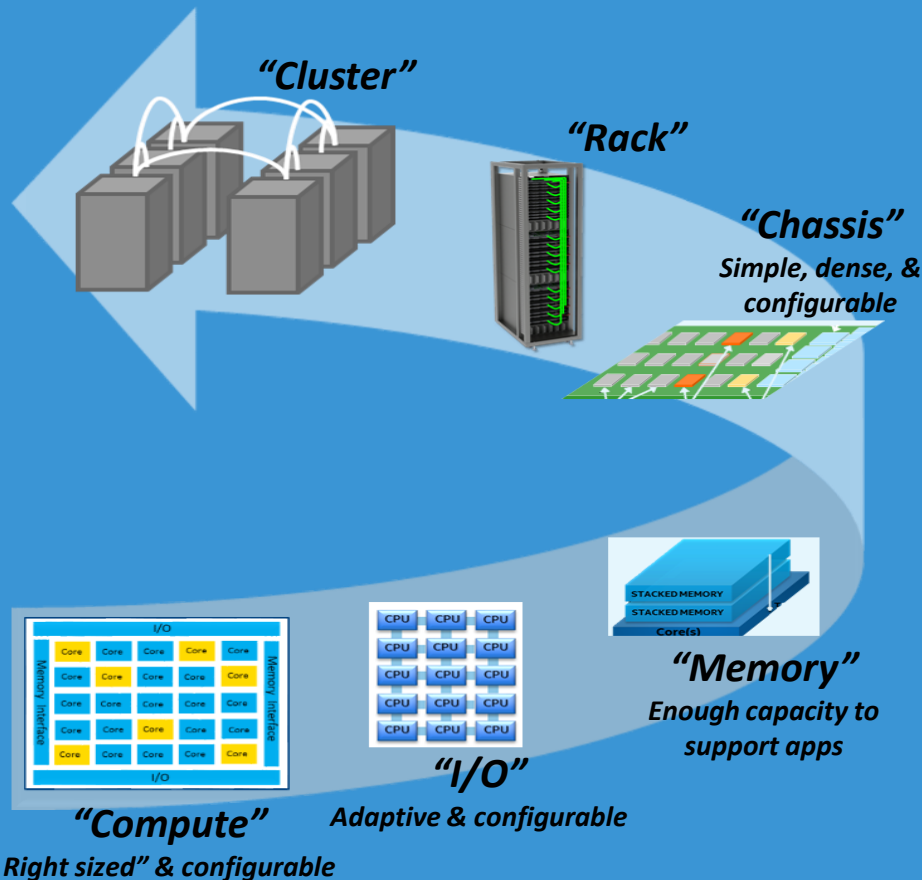
Intel® True Scale Fabric  
Intel® Omni-Path Fabric  
Intel® Ethernet  
Intel® Silicon Photonics  
Technology

Next-generation NVM  
Intel® SSDs  
Intel® Lustre\*-based Solutions

Intel® Software Tools  
Intel Cluster Software

# SSF: Enabling Configurability & Scalability

*from components to racks to clusters*

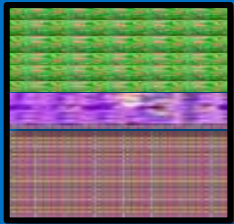


- Intel Xeon or Xeon Phi processors based on workloads
- Compute flexibly aggregated
- Low latency compute to compute interconnect

- I/O Topologies for high performance
- Configurable I/O bandwidth director switch
- Burst buffer to decouple storage from I/O

# SSF: Accommodating New Compute Paradigms

*Today*

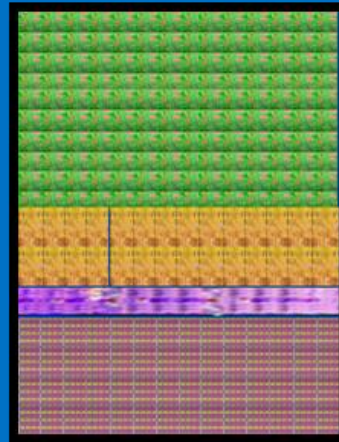


*Multi-Core*



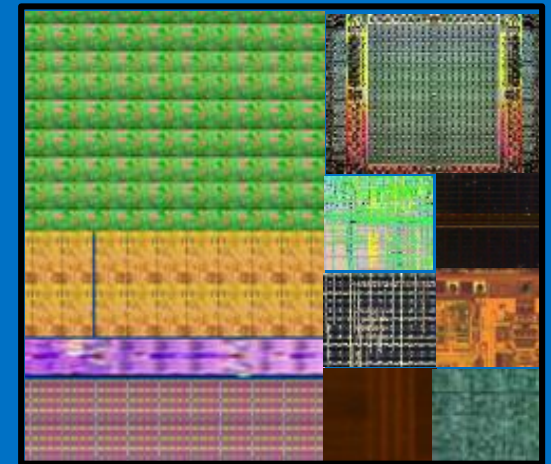
*Many-Core*

*Next*



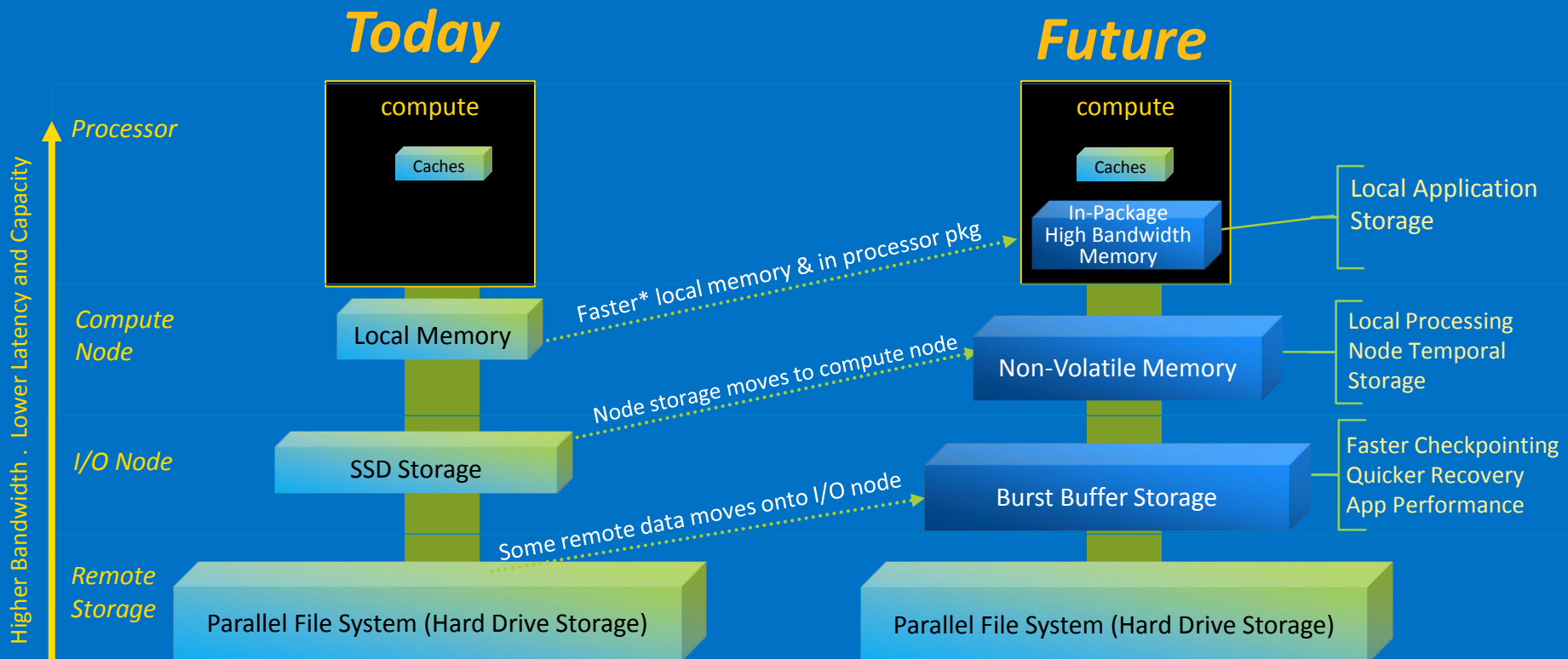
*Integrating  
Mixed Cores*

*The Future*



*Integrating  
FPGA, Accelerators....*

# SSF: Re-architecting The Memory-Storage Hierarchy

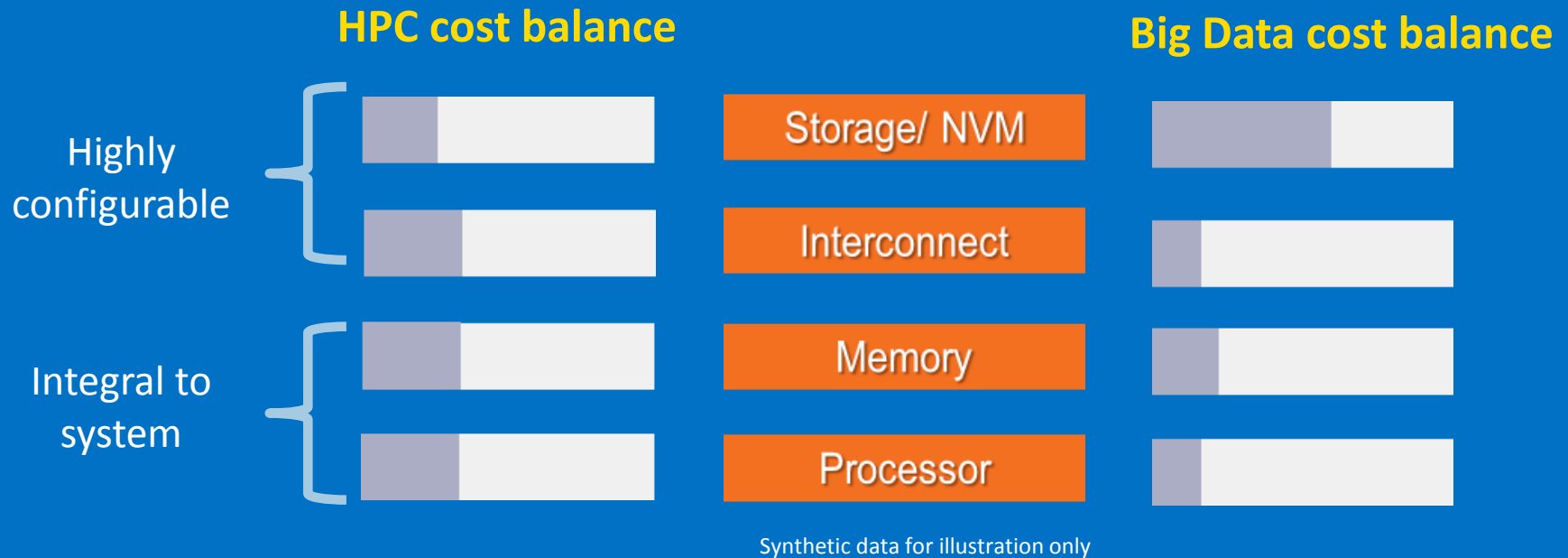


*Better data-intensive app performance and energy efficiency*

\*Compared to standard DDR memory

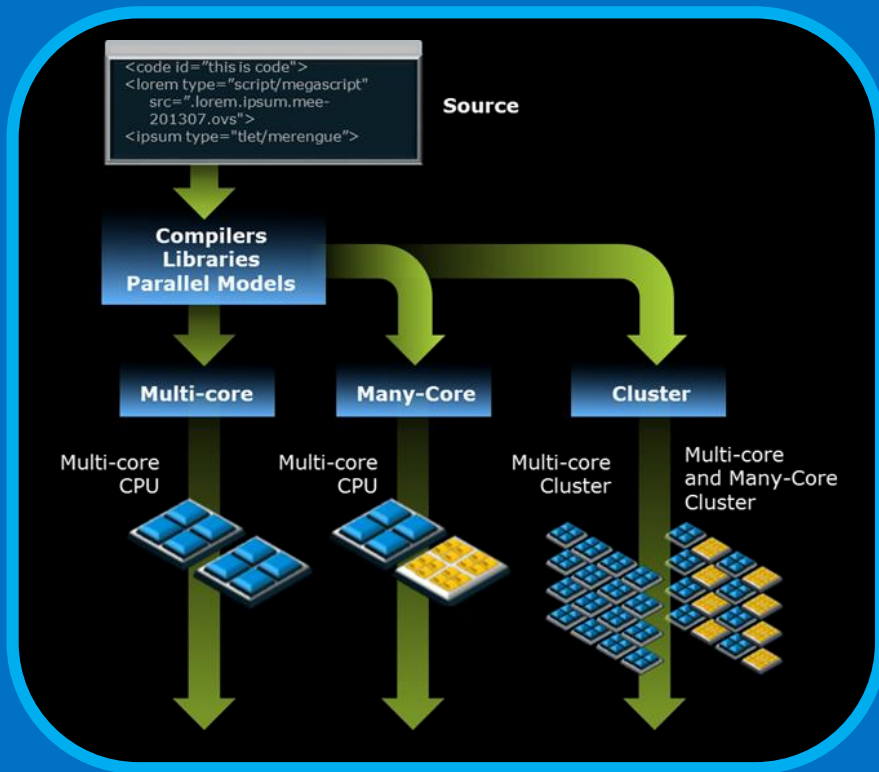


# SSF: End The “Big Data vs. HPC” Debate



*A single, broadly configurable, framework to meet both requirements from a hardware perspective*

# SSF: Enabling A Single Programming Model



Instruction  
Parallelism

Data  
Parallelism

Thread  
Parallelism

Cluster /  
Process  
Parallelism

## Serial Code

Fast Scalar performance, Optimized C/C++, FORTRAN, Threading and Performance Libraries, Debug / Analysis Tools

## Parallel Node Level

Multi-core, Multi-Socket, SSE and AVX instructions, OpenMP, Threading and Performance Libraries, Thread Checker, Ct

## Multi-Node / Cluster Level

Cluster Tools, Cluster OpenMP, MPI Checker

*Unlike accelerators, optimizations for Intel® Xeon Phi™ and Intel® Xeon® products share the same languages, directives, libraries, and tools*

# Modernizing Community Codes

*Together With You*

Intel Parallel  
Computing  
Centers

50+ Centers  
14 countries  
80+ codes



# Heading To The Era of SSF

*ANL selected Intel and Cray for Extreme Scale HPC*



**Cori**  
NERSC‡  
**>30PF**

April '14

**Trinity**  
NNSA†  
**>40PF**  
July '14

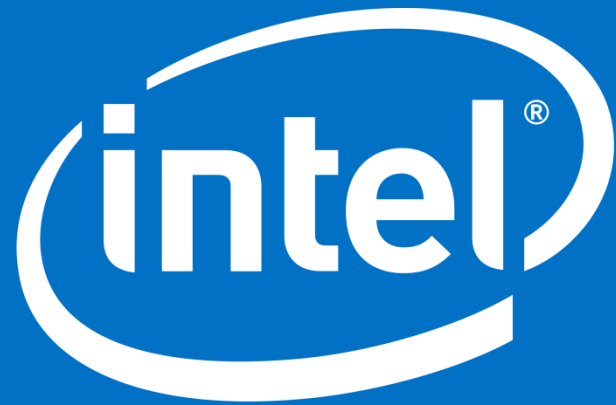
**Aurora**  
Argonne National Laboratory  
**>180PF**  
**CRAY**  
April '15

**+**  
**Theta**  
Argonne National Laboratory  
**>8.5PF**  
**>\$200M**

‡ Cray XC Series at National Energy Research Scientific Computing Center (NERSC).

† Cray XC Series at National Nuclear Security Administration (NNSA).

\*Other names and brands may be claimed as the property of others.



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